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Practitioner's Docket No.: M-11443

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of (1st Inventor): Lee John Smith

Assignee: Amkor Technology, Inc.

Serial No.: 09/944,732-2003

Group No.: 2827

Filed: 08/31/2001

Examiner: David E. Graybill

For: "Thin Semiconductor Package Including Stacked Dies"

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Date: March 24, 2003

Assistant Commissioner of Patents and Trademarks  
Washington, D.C. 20231

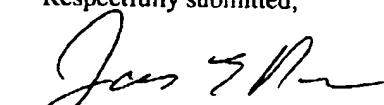
STATUS INQUIRY

Sir:

More than twelve months have passed since the filing of this application on 08/31/2001. No communication has been received from the Patent and Trademark Office indicating action on this application.

Kindly advise the undersigned of the present status of this application.

Respectfully submitted,

  
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